BUREAU VERITAS
Certification

DISCO CORPORATION

This is a multi-site certificate, additional site(s) are listed on the next page(s)

13-11, Omori-Kita 2-chome, Ota-ku, Tokyo, 143-8580, Japan

Bureau Veritas Certification Holding SAS -UK Branch certifies that the Management System of the above organisation has been audited and found to be in accordance with the requirements of the management system standards detailed below

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ISO9001:2015, JIS Q 9001:2015

Scope of certification

- **Design / development, manufacturing, installation / maintenance services and supply of service parts of precision processing machines and systems for cutting, grinding and polishing of silicon wafers and other materials.**
- **Design / development and manufacturing of precision processing tools for cutting, grinding and polishing of silicon wafers and other materials.**
- **Design / development and manufacturing of functional consumables (assisting materials) for cutting, grinding and polishing of silicon wafers and other materials.**
- **Design / development and manufacturing of abrasive cut-off wheels.**
- **Supply of precision processing services.**
- **Supply of on-site electronics processing services.**
- **Design / development, manufacturing, repair, and supply of maintenance parts of various types of power sources, power generators, and motors.**

Original cycle start date:	**11 AUGUST 1995**
Expiry date of previous cycle:	**N/A**
Recertification Audit date:	**05 JULY 2024**
Recertification cycle start date:	**05 AUGUST 2024**

Subject to the continued satisfactory operation of the organisation's Management System,
this certificate expires on: **10 AUGUST 2027**

Certificate No. **22082636** Version: **2.0** Revision date: **04 MARCH 2025**

UKAS
MANAGEMENT
SYSTEMS
0008

Certification body address: 5th Floor, 100 Lower Thames Street, London, EC3R 6DL, United Kingdom

Local office: Bureau Veritas Japan Co., Ltd. Certification Division

KRC bldg. 8F, 18, Nihon-odori, Naka-ku, Yokohama, 231-0021, Japan

Further clarifications regarding the scope of this certificate and the applicability of the management system requirements may be obtained by consulting the organisation.
To check this certificate validity please call: **+81 (0)45-651-4784**

BUREAU VERITAS
Certification

DISCO CORPORATION

ISO9001:2015, JIS Q 9001:2015

Scope of certification

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- Design / development and manufacturing of precision processing tools for cutting, grinding and polishing of silicon wafers and other materials.
- Design / development and manufacturing of functional consumables (assisting materials) for cutting, grinding and polishing of silicon wafers and other materials.
- Design / development and manufacturing of abrasive cut-off wheels.
- Supply of precision processing services.
- Supply of on-site electronics processing services.
- Design / development, manufacturing, repair, and supply of maintenance parts of various types of power sources, power generators, and motors.

Site Name	Site Address	Site Scope
DISCO Corporation Head Office	13-11, Omori-Kita 2-chome, Ota-ku, Tokyo, 143-8580, Japan	・Design / development and sales, installation / maintenance services, and supply of service parts of precision processing machines and systems for cutting, grinding and polishing of silicon wafer and other materials. ・Design / development and sales of precision processing tools for cutting, grinding and polishing of silicon wafer and other materials. ・Design / development and sales of functional consumables (assisting materials) for cutting, grinding and polishing of silicon wafer and other materials. ・Supply of precision processing services.
Haneda R&D Center	7-56, Higashikojiya 6-chome, Ota-ku, Tokyo, 144-0033, Japan	・Manufacturing of precision processing machines and systems for cutting, grinding and polishing of silicon wafer and other materials.

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- **Design / development and manufacturing of abrasive cut-off wheels.**
- **Supply of precision processing services.**
- **Supply of on-site electronics processing services.**
- **Design / development, manufacturing, repair, and supply of maintenance parts of various types of power sources, power generators, and motors.**

Site Name	Site Address	Site Scope
Kure Plant	1-23, Hiro Bunka-cho, Kure-shi, Hiroshima, 737-0198, Japan	・Manufacturing and sales of precision processing tools for cutting, grinding and polishing of silicon wafer and other materials. ・Design / development, manufacturing and sales of abrasive cut-off wheels.
Kuwabata Plant	4010-1, Gohara-cho, Kure-shi, Hiroshima, 737-0161, Japan	・Design / development and manufacturing of precision processing machines and systems for cutting, grinding and polishing of silicon wafer and other materials. ・Design / development and manufacturing of precision processing tools for cutting, grinding and polishing of silicon wafer and other materials. ・Manufacturing of functional consumables (assisting materials) for cutting, grinding and polishing of silicon wafer and other materials.
Chino Plant	480, Toyohira, Chino-shi, Nagano, 391-0297, Japan	・Design / development and manufacturing of precision processing machines and systems for cutting, grinding and polishing of silicon wafer and other materials. ・Manufacturing of precision processing tools for cutting, grinding and polishing of silicon wafer and other materials.

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- Design / development and manufacturing of functional consumables (assisting materials) for cutting, grinding and polishing of silicon wafers and other materials.
- Design / development and manufacturing of abrasive cut-off wheels.
- Supply of precision processing services.
- Supply of on-site electronics processing services.
- Design / development, manufacturing, repair, and supply of maintenance parts of various types of power sources, power generators, and motors.

Site Name	Site Address	Site Scope
Osaka Branch Office	3-16, Senba-higashi 3-chome, Minoh-shi, Osaka, 562-0035, Japan	・Sales, installation / maintenance services, and supply of service parts of precision processing machines and systems for cutting, grinding and polishing of silicon wafer and other materials. ・Sales of precision processing tools for cutting, grinding and polishing of silicon wafer and other materials. ・Sales of functional consumables (assisting materials) for cutting, grinding and polishing of silicon wafer and other materials. ・Sales of abrasive cut-off wheels.
Kyushu Branch Office	2170-4, Tabaru, Mashiki-machi, Kamimashiki-gun, Kumamoto, 861-2202, Japan	・Sales, installation / maintenance services, and supply of service parts of precision processing machines and systems for cutting, grinding and polishing of silicon wafer and other materials. ・Sales of precision processing tools for cutting, grinding and polishing of silicon wafer and other materials. ・Sales of functional consumables (assisting materials) for cutting, grinding and polishing of silicon wafer and other materials.

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- Design / development and manufacturing of functional consumables (assisting materials) for cutting, grinding and polishing of silicon wafers and other materials.
- Design / development and manufacturing of abrasive cut-off wheels.
- Supply of precision processing services.
- Supply of on-site electronics processing services.
- Design / development, manufacturing, repair, and supply of maintenance parts of various types of power sources, power generators, and motors.

Site Name	Site Address	Site Scope
Sendai Branch Office	5-1, Honcho 2-chome, Aoba-ku, Sendai-shi, Miyagi, 980-0014, Japan	・Sales, installation / maintenance services, and supply of service parts of precision processing machines and systems for cutting, grinding and polishing of silicon wafer and other materials. ・Sales of precision processing tools for cutting, grinding and polishing of silicon wafer and other materials. ・Sales of functional consumables (assisting materials) for cutting, grinding and polishing of silicon wafer and other materials.
DISCO HI-TEC TAIWAN CO., LTD.	1F, 9F., No.188, Baoqiao Rd., Xindian Dist., New Taipei City, Taiwan (R.O.C.)	・Sales, installation / maintenance services, and supply of service parts of precision processing machines and systems for cutting, grinding and polishing of silicon wafer and other materials. ・Sales of precision processing tools for cutting, grinding and polishing of silicon wafer and other materials. ・Sales of functional consumables (assisting materials) for cutting, grinding and polishing of silicon wafer and other materials.

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- **Supply of precision processing services.**
- **Supply of on-site electronics processing services.**
- **Design / development, manufacturing, repair, and supply of maintenance parts of various types of power sources, power generators, and motors.**

Site Name	Site Address	Site Scope
DISCO HI-TEC AMERICA, INC.	5921 Optical Ct., San Jose, CA 95138, U.S.A.	・Sales, installation / maintenance services, and supply of service parts of precision processing machines and systems for cutting, grinding and polishing of silicon wafer and other materials. ・Sales of precision processing tools for cutting, grinding and polishing of silicon wafer and other materials. ・Sales of functional consumables (assisting materials) for cutting, grinding and polishing of silicon wafer and other materials. ・Supply of precision processing services.
DISCO HI-TEC (SINGAPORE) PTE LTD	80 Ubi Avenue 4, #06-01 Singapore 408831	・Sales, installation / maintenance services, and supply of service parts of precision processing machines and systems for cutting, grinding and polishing of silicon wafer and other materials. ・Sales of precision processing tools for cutting, grinding and polishing of silicon wafer and other materials. ・Sales of functional consumables (assisting materials) for cutting, grinding and polishing of silicon wafer and other materials.

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- **Supply of on-site electronics processing services.**
- **Design / development, manufacturing, repair, and supply of maintenance parts of various types of power sources, power generators, and motors.**

Site Name	Site Address	Site Scope
DISCO HI-TEC EUROPE GmbH	Liebigstrasse 8, D-85551 Kirchheim b. Muenchen, Germany	・Sales, installation / maintenance services, and supply of service parts of precision processing machines and systems for cutting, grinding and polishing of silicon wafer and other materials. ・Sales of precision processing tools for cutting, grinding and polishing of silicon wafer and other materials. ・Sales of functional consumables (assisting materials) for cutting, grinding and polishing of silicon wafer and other materials. ・Supply of precision processing services.
DISCO HI-TEC KOREA Corporation	3F, DHK Solution Bldg., 28, Pangyo-ro 255beon-gil, Bundang-gu, Seongnam-si, Gyeonggi-do, Korea 13486	・Sales, installation / maintenance services, and supply of service parts of precision processing machines and systems for cutting, grinding and polishing of silicon wafer and other materials. ・Sales of precision processing tools for cutting, grinding and polishing of silicon wafer and other materials. ・Sales of functional consumables (assisting materials) for cutting, grinding and polishing of silicon wafer and other materials.

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- **Supply of on-site electronics processing services.**
- **Design / development, manufacturing, repair, and supply of maintenance parts of various types of power sources, power generators, and motors.**

Site Name	Site Address	Site Scope
DISCO KKM FACTORIES, LTD.	13-11, Omori-Kita 2-chome, Ota-ku, Tokyo, 143-0016, Japan	Supply of on-site electronics processing services.
DAIICHI COMPONENTS, LTD. HEAD OFFICE	13-11, Omori-Kita 2-chome, Ota-ku, Tokyo, 143-0016, Japan	Sales of various types of power sources, power generators, and motors.
DAIICHI COMPONENTS, LTD. CHINO PLANT	480, Toyohira, Chino-shi, Nagano, 391-0294, Japan	Design / development, manufacturing, repair, and supply of maintenance parts of various types of power sources, power generators, and motors.
DISCO Manufacturing Corporation Hiroshima Works	2507-913, Gohara-cho, Kure-shi, Hiroshima, 737-0161, Japan	Manufacturing of precision processing machines and systems for cutting, grinding and polishing of silicon wafer and other materials.

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